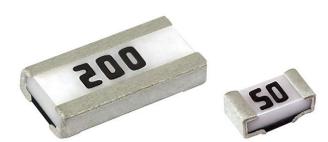
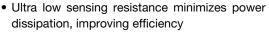


Metal Foil Current Sense Resistors, Very High Power (to 2 W)



FEATURES





 Wide side terminal construction (0508 and 0612) for lower ESL ROHS
COMPLIANT
HALOGEN
FREE
GREEN

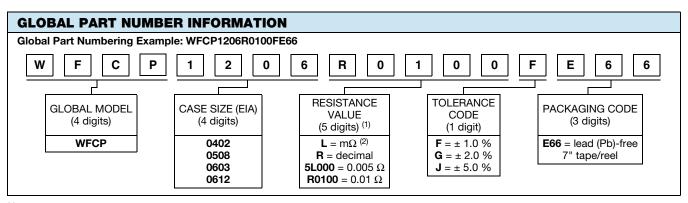
(5-2008)

- High power to foot print size ratio (2 W in 0612 and 0.5 W in 0508)
- Sulfur resistant
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

APPLICATIONS

- Switching power supply
- Voltage regulation module
- DC/DC converter, adaptor, battery pack, charger
- Pad and cell phone
- · Power management

STANDARD ELECTRICAL SPECIFICATIONS								
GLOBAL MODEL	SIZE	POWER RATING W	TOLERANCE %	RESISTANCE VALUE RANGE Ω	WEIGHT (typical) g/1000 pieces			
WFCP0402	0402	0.25	± 1, ± 2, ± 5	0.0025 to 0.05	1.1			
WFCP0508	0508	0.5	± 1, ± 2, ± 5	0.005 to 0.03	6.8			
	0508	1.0	± 1, ± 2, ± 5	0.001 to 0.004	6.8			
WFCP0603	0603	0.5	± 1, ± 2, ± 5	0.002 to 0.04	3.3			
WFCP0612	0612	1.0	± 1, ± 2, ± 5	0.0051 to 0.03	14.7			
	0612	2.0	± 1, ± 2, ± 5	0.001 to 0.005	14.7			



Notes

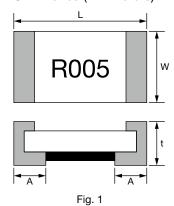
(1) Resistance values are available per E12 and E24 decades; www.vishay.com/doc?28372

(2) Use "L" for resistance values < 0.01 Ω



TECHNICAL SPECIFICATIONS								
PARAMETER	LIMIT	RESISTOR CHARACTERISTICS						
PARAMETER	UNIT	WFCP0402	WFCP0508	WFCP0603	WFCP0612			
T	ppm/°C	\pm 100 for 5.1 m Ω to 50 m Ω	\pm 75 for 5 m Ω to 30 m Ω	\pm 75 for 10 m Ω to 40 m Ω	\pm 75 for 5.1 m Ω to 30 m Ω			
Temperature coefficient		\pm 150 for 2.5 m Ω to 5 m Ω	\pm 150 for 1 m Ω to 4 m Ω	\pm 100 for 2 m Ω to 9 m Ω	\pm 100 for 1 m Ω to 5 m Ω			
Operating temperature range	°C	-55 to +170						
Maximum working voltage	V	$(P \times R)^{1/2}$						
Maximum element temperature	°C	170						

DIMENSIONS in inches (millimeters)



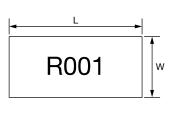


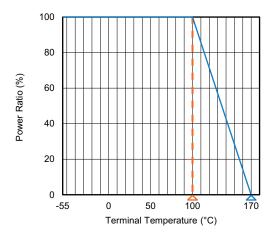


Fig. 2

TYPE	RESISTANCE		DIMENSIONS				
(INCH SIZE)	RANGE (m Ω)	L	W	t	Α	FIG.	
	2.5 to 5				0.45 ± 0.1	1	
WFCP0402	5 to 7	1.00 ± 0.1	0.55 ± 0.1	0.45 ± 0.10	0.35 ± 0.1	1	
	8 to 50				0.25 ± 0.1	1	
WECDOEOS	1 to 4	1.35 ± 0.3	2.00 ± 0.2	0.45 ± 0.15	0.40 ± 0.25	2	
WFCP0508	5 to 30	1.30 ± 0.2	2.00 ± 0.2	0.60 ± 0.20	0.30 ± 0.2	1	
WFCP0603	2 to 40	1.60 ± 0.1	0.80 ± 0.1	0.55 ± 0.15	0.30 ± 0.2	1	
WEODOCIO	1 to 5	1.60 ± 0.2	3.20 ± 0.20	0.75 ± 0.25	0.30 ± 0.2	2	
WFCP0612	5 to 30	1.00 ± 0.2		0.60 ± 0.20		1	

Note

DERATING



^{• 0402} has no marking; 0508, 0603, and 0612 marking shows two digits for resistance

PERFORMANCES

NO.	ITEM	TEST CONDITION	SPECIFICATION
1 (1)	Short time overload	5 times rated power for 5 seconds (JIS-C5202-5.5)	ΔR : ± (1 % + 0.0005 Ω)
2	Temperature coefficient of resistance (TCR)	+25 °C / +125 °C (JIS-C5202-5.2) TCR (ppm/°C) = $\frac{\Delta R}{R \times \Delta t} \times 10^6$	Refer to Electrical Specification
3	Damp heat with load	The specimens shall be placed in a chamber and subjected to a relative humidity of 90 % to 95 % and a temperature of 40 °C ± 2 °C for the period of 1000 hours with applying rated power 1.5 hours ON and 0.5 hour OFF. (MIL-STD-202, method 103)	ΔR : ± (1 % + 0.0005 Ω)
4	High temperature exposure	The chip (mounted on board) is exposed in the heat chamber 125 $^{\circ}$ C \pm 3 $^{\circ}$ C for 1000 hours. (JIS-C5202-7.2)	ΔR : ± (1 % + 0.0005 Ω)
5	Load life	Apply rated power at 70 °C ± 2 °C for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR : ± (1 % + 0.0005 Ω)
6	Rapid change of temperature	The chip (mounted on board) is exposed, -55 °C \pm 3 °C (30 min.) / +155 °C \pm 2 °C (30 min.) for 5 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature +155 (\pm 2) °C +25 (\pm 2) °C +25 (\pm 2) °C +25 (\pm 3) °C 1 cycle	ΔR : ± (1 % + 0.0005 Ω)

Note

(1) WFCP0612 short term overload is 3 times for 5 seconds

FUN	FUNCTION PERFORMANCE							
NO.	ITEM	TEST CONDITION	SPECIFICATION					
1	Bending strength	Mount the chip to test substrate. Apply pressure in direction of arrow unit band width reaches 2 mm (\pm 0.2 / \pm 0 mm) illustrated in the figure below and hold for 10 s \pm 1 s. (JIS-C5202-6.1) Unit: mm Position before bend Testing printed circuit board	ΔR : ± (1 % + 0.0005 Ω)					
2	Solvent resistance	Complete immersion of specimens in isopropyl alcohol for 3 (+5, -0) min. 25 $^{\circ}$ C ± 5 $^{\circ}$ C. (MIL-STD-202, method 215)	Verify marking permanency. (not required for laser etched parts or parts with no marking					
3	Resistance to solder heat	The specimen chip shall be immersed into the flux specified in the solder bath 260 °C \pm 5 °C for 10 s \pm 1 s. (MIL-STD-202, method 210)	Δ <i>R</i> : ± (1 % + 0.0005 Ω)					



FUN	FUNCTION PERFORMANCE							
NO.	ITEM	TEST CONDITION	SPECIFICATION					
4	Solderability	The specimen chip shall be immersed into the flux specified in the solder bath 235 °C ± 5 °C for 2 s ± 0.5 s. It shall be immersed to a point 10 mm from its root. (Sn96.5 / Ag3.0 / Cu0.5) (JIS-C5 202-6.11) Molten solder Specimen SMD H H H H H H H H H H H H H H H H H H H	Solder shall be covered 95 % or more of the electrode area.					

Notes

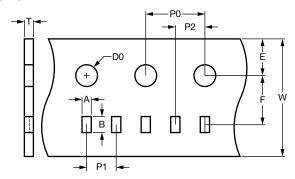
- The surface temperature of component should below 100 °C
- 0.5 W with total solder pad trace size of 100 mm²
- 1.0 W with total solder pad trace size of 150 mm²
- 2.0 W with total solder pad trace size of 300 mm²
- 3.0 W with total solder pad trace size of 450 mm²

TAPE PACKAGING SPECIFICATIONS							
MODEL	REEL						
MODEL	TAPE WIDTH	DIAMETER	PIECES / REEL				
WFCP0402	Embossed paper tape	178 mm / 7"	10 000				
WFCP0508 WFCP0603 WFCP0612	Embossed paper tape	178 mm / 7"	5000				

Note

• Embossed carrier tape per EIA (EIAJ)

PAPER TAPE SPECIFICATIONS



TYPE	CARRIER DIMENSIONS (in millimeters)									
ITPE	Α	В	E	F	W	P0	P1	P2	D0	Т
WFCP0402	0.7 ± 0.05	1.2 ± 0.05	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	2.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.6 ± 0.1
WFCP0508	1.6 ± 0.1	2.4 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.97 ± 0.1
WFCP0603	1.1 ± 0.1	1.8 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.70 ± 0.1
WFCP0612	2.0 ± 0.1	3.6 ± 0.1	1.75 ± 0.1	3.5 ± 0.05	8.0 ± 0.2	4.0 ± 0.1	4.0 ± 0.1	2.0 ± 0.05	1.55 ± 0.05	0.97 ± 0.1

Notes

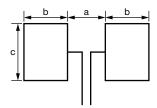
- Embossed carrier tape per EIA (EIAJ)
- Additional packaging details at www.vishay.com/doc?20051



STORAGE CONDITIONS

Temperature: 5 °C to 35 °C, humidity: 40 % to 75 %

RECOMMENDED SOLDER PAD LAYOUT



TYPE	PAD LAYOUT DIMENSIONS (in millimeters)					
1172	а	b	С			
0402 (8 m Ω to 50 m Ω)	0.50	0.50	0.60			
0402 (2.5 m Ω to 7 m Ω)	0.30	0.60	0.60			
0508 (1 m Ω to 30 m Ω)	0.50	1.30	2.60			
0603 (2 mΩ to 9 mΩ)	0.60	0.90	1.00			
0603 (9.1 mΩ to 40 mΩ)	0.90	0.70	1.00			
0612 (5.1 mΩ to 30 mΩ)	0.60	1.30	3.60			
0612 (1 mΩ to 5 mΩ)	0.60	1.30	3.80			

Note

• Recommend to use the steel plate which thickness $> 100 \ \mu m$ to avoid the insufficient solder height

SOLDERING RECOMMENDATIONS

- Peak reflow temperatures and durations:
 - IR reflow peak = 260 °C max. for 10 s
 - Wave solder = 260 °C max. for 10 s
- Compatible with lead and lead (Pb)-free solder reflow processes
- Recommended IR reflow profile for surface mount devices: www.vishay.com/doc?31052

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